

**GJ01L60**

N-CHANNEL ENHANCEMENT MODE POWER MOSFET

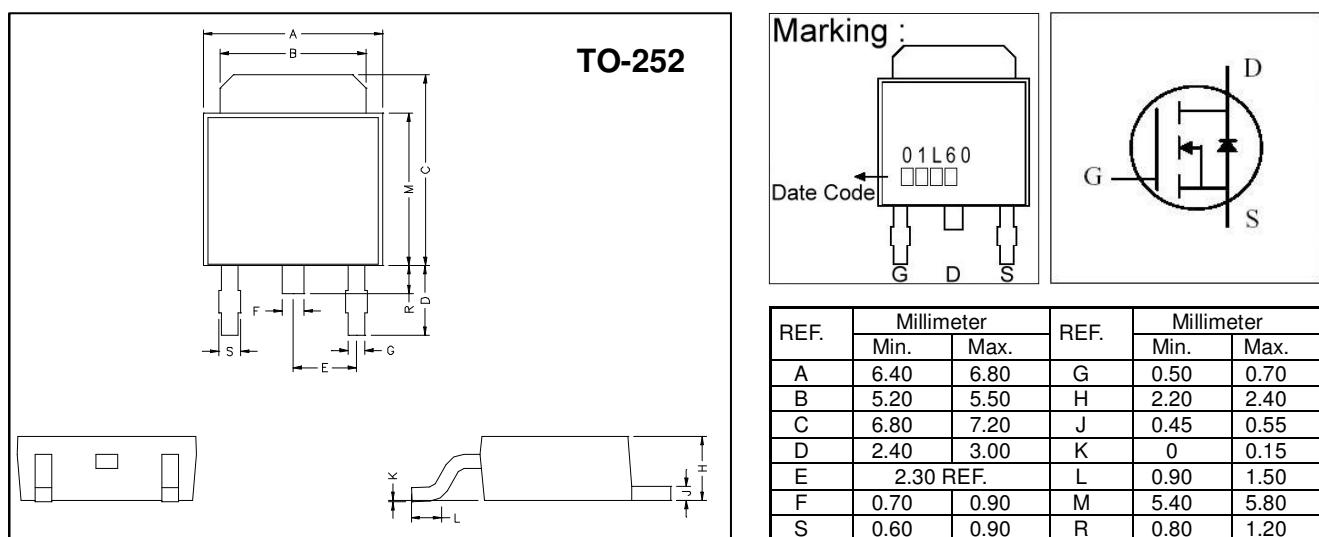
BVDSS	600V
RDS(ON)	12Ω
ID	1A

**Description**

The GJ01L60 (TO-252) is universally preferred for all commercial-industrial surface mount applications and suited for AC/DC converters.

**Features**

- \*Repetitive Avalanche Rated
- \*Simple Drive Requirement
- \*Fast Switching Speed
- \*RoHS Compliant

**Package Dimensions****Absolute Maximum Ratings**

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V <sub>DS</sub>	600	V
Gate-Source Voltage	V <sub>GS</sub>	±30	V
Continuous Drain Current, V <sub>GS</sub> @10V	I <sub>D</sub> @T <sub>c</sub> =25°C	1	A
Continuous Drain Current, V <sub>GS</sub> @10V	I <sub>D</sub> @T <sub>c</sub> =100°C	0.8	A
Pulsed Drain Current <sup>1</sup>	I <sub>DM</sub>	3	A
Total Power Dissipation	P <sub>D</sub> @T <sub>c</sub> =25°C	29	W
Linear Derating Factor		0.232	W/°C
Single Pulse Avalanche Energy <sup>2</sup>	E <sub>AS</sub>	0.5	mJ
Avalanche Current	I <sub>AR</sub>	1	A
Repetitive Avalanche Energy	E <sub>AR</sub>	0.5	mJ
Operating Junction and Storage Temperature Range	T <sub>j</sub> , T <sub>stg</sub>	-55 ~ +150	°C

**Thermal Data**

Parameter	Symbol	Value	Unit
Thermal Resistance Junction-case	R <sub>thj-case</sub>	4.3	°C/W
Thermal Resistance Junction-ambient	R <sub>thj-amb</sub>	110	°C/W

## Electrical Characteristics ( $T_j = 25^\circ\text{C}$ unless otherwise specified)

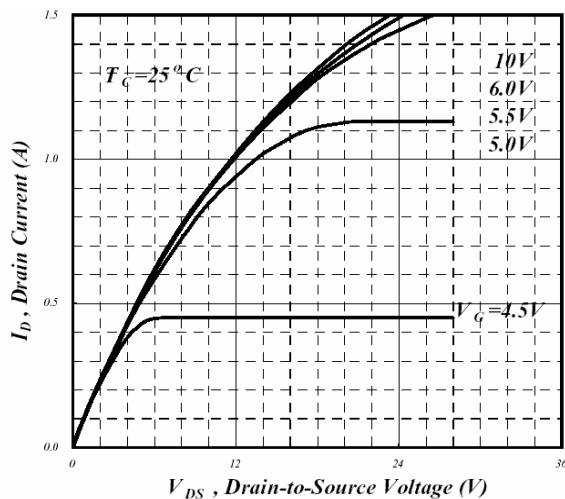
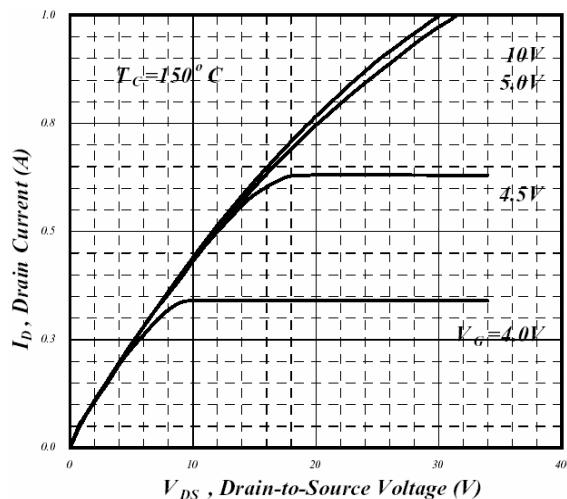
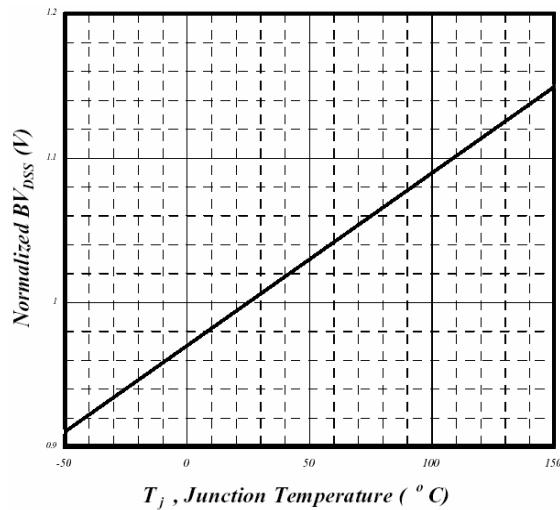
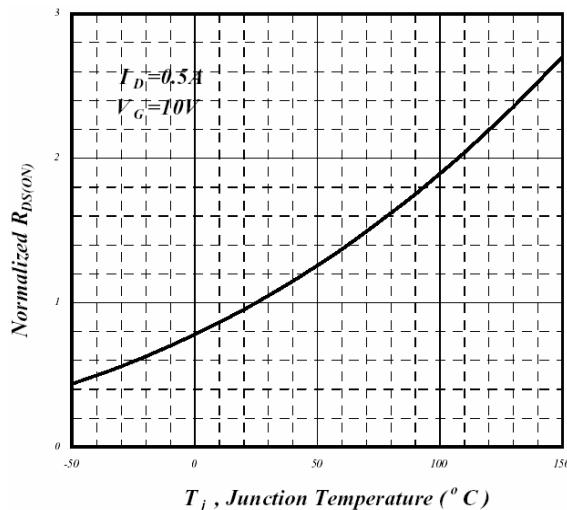
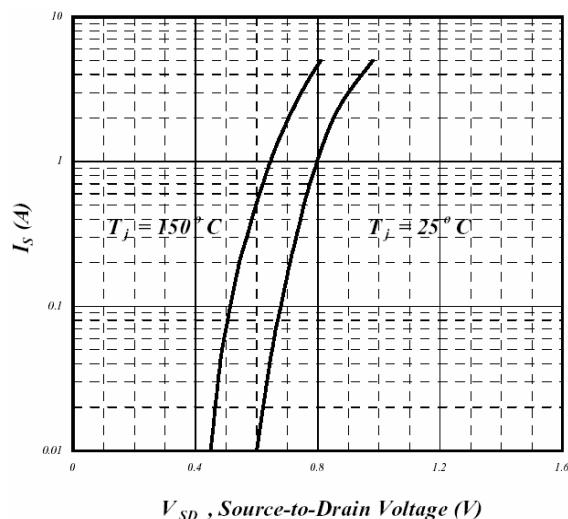
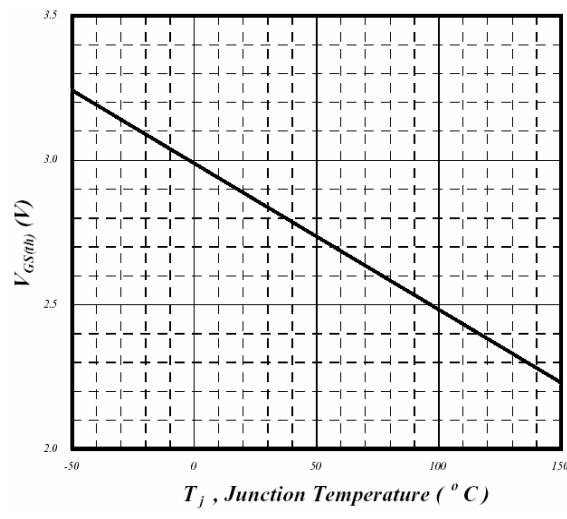
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	600	-	-	V	$\text{V}_{\text{GS}}=0, \text{I}_D=1\text{mA}$
Breakdown Voltage Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}} / \Delta T_j$	-	0.8	-	V/ $^\circ\text{C}$	Reference to $25^\circ\text{C}$ , $\text{I}_D=1\text{mA}$
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	2.0	-	4.0	V	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$
Forward Transconductance	$\text{g}_{\text{fs}}$	-	0.8	-	S	$\text{V}_{\text{DS}}=10\text{V}, \text{I}_D=0.5\text{A}$
Gate-Source Leakage Current	$\text{I}_{\text{GSS}}$	-	-	$\pm 100$	nA	$\text{V}_{\text{GS}}= \pm 30\text{V}$
Drain-Source Leakage Current( $T_j=25^\circ\text{C}$ )	$\text{I}_{\text{DSS}}$	-	-	10	$\mu\text{A}$	$\text{V}_{\text{DS}}=600\text{V}, \text{V}_{\text{GS}}=0$
Drain-Source Leakage Current( $T_j=150^\circ\text{C}$ )		-	-	100	$\mu\text{A}$	$\text{V}_{\text{DS}}=480\text{V}, \text{V}_{\text{GS}}=0$
Static Drain-Source On-Resistance <sup>3</sup>	$\text{R}_{\text{DS}(\text{ON})}$	-	-	12	$\Omega$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=0.5\text{A}$
Total Gate Charge <sup>3</sup>	$\text{Q}_g$	-	4.0	-	nC	$\text{I}_D=1\text{A}$ $\text{V}_{\text{DS}}=480\text{V}$ $\text{V}_{\text{GS}}=10\text{V}$
Gate-Source Charge	$\text{Q}_{\text{gs}}$	-	1.0	-		
Gate-Drain ("Miller") Change	$\text{Q}_{\text{gd}}$	-	1.1	-		
Turn-on Delay Time <sup>2</sup>	$\text{T}_{\text{d}(\text{on})}$	-	6.6	-	ns	$\text{V}_{\text{DD}}=300\text{V}$ $\text{I}_D=1\text{A}$ $\text{V}_{\text{GS}}=10\text{V}$ $\text{R}_G=3.3\Omega$ $\text{R}_D=300\Omega$
Rise Time	$\text{T}_r$	-	5.0	-		
Turn-off Delay Time	$\text{T}_{\text{d}(\text{off})}$	-	11.7	-		
Fall Time	$\text{T}_f$	-	9.2	-		
Input Capacitance	$\text{C}_{\text{iss}}$	-	170	-	pF	$\text{V}_{\text{GS}}=0\text{V}$ $\text{V}_{\text{DS}}=25\text{V}$ $f=1.0\text{MHz}$
Output Capacitance	$\text{C}_{\text{oss}}$	-	30.7	-		
Reverse Transfer Capacitance	$\text{C}_{\text{rss}}$	-	5.1	-		

## Source-Drain Diode

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Forward On Voltage <sup>3</sup>	$\text{V}_{\text{SD}}$	-	-	1.2	V	$\text{I}_S=1\text{A}, \text{V}_{\text{GS}}=0\text{V}, \text{T}_j=25^\circ\text{C}$
Continuous Source Current (Body Diode)	$\text{I}_S$	-	-	1	A	$\text{V}_D=\text{V}_G=0\text{V}, \text{V}_S=1.2\text{V}$
Pulsed Source Current (Body Diode) <sup>1</sup>	$\text{I}_{\text{SM}}$	-	-	5	A	

Notes: 1. Pulse width limited by safe operating area.

2. Staring  $\text{T}_j=25^\circ\text{C}$ ,  $\text{V}_{\text{DD}}=50\text{V}$ ,  $L=1.0\text{mH}$ ,  $\text{R}_G=25\Omega$ ,  $\text{I}_{\text{AS}}=1.0\text{A}$ .
3. Pulse width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .

**Characteristics Curve****Fig 1. Typical Output Characteristics****Fig 2. Typical Output Characteristics****Fig 3. Normalized  $BV_{DSS}$  v.s. Junction Temperature****Fig 4. Normalized On-Resistance v.s. Junction Temperature****Fig 5. Forward Characteristics of Reverse Diode****Fig 6. Gate Threshold Voltage v.s. Junction Temperature**

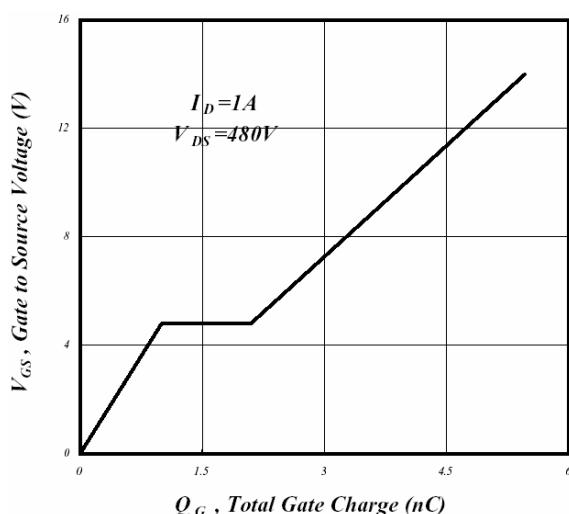


Fig 7. Gate Charge Characteristics

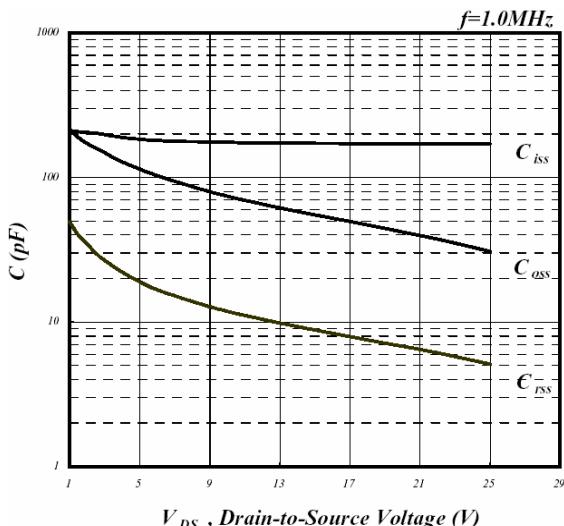


Fig 8. Typical Capacitance Characteristics

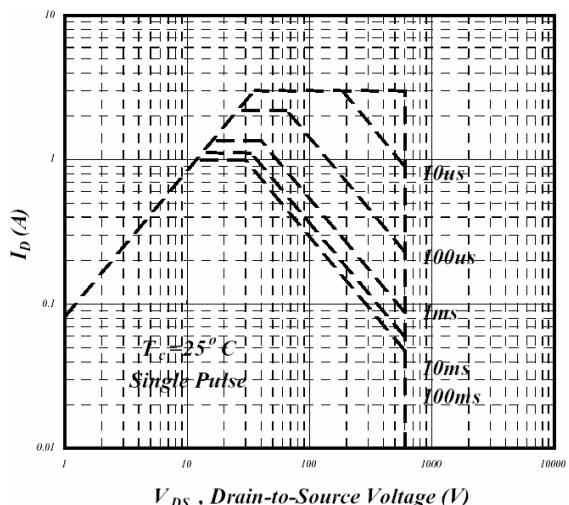


Fig 9. Maximum Safe Operating Area

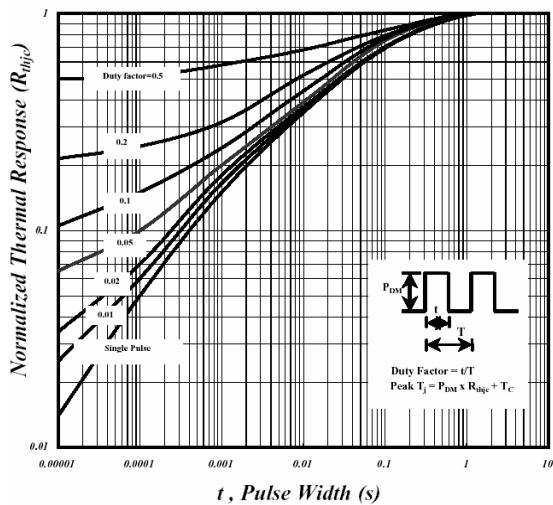


Fig 10. Effective Transient Thermal Impedance

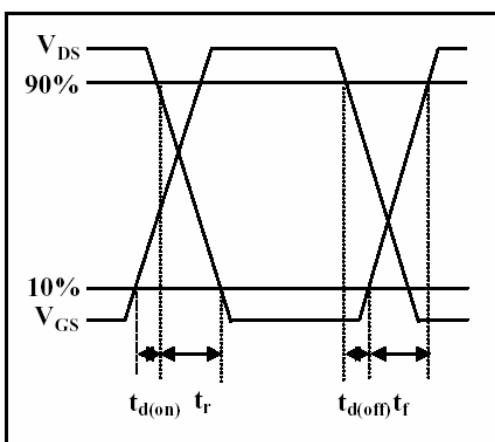


Fig 11. Switching Time Waveform

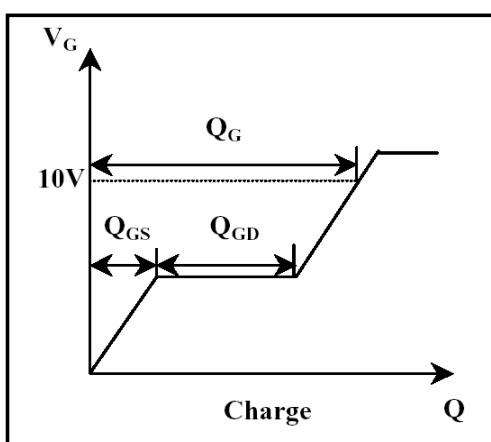


Fig 12. Gate Charge Waveform

**Important Notice:**

- All rights are reserved. Reproduction in whole or in part is prohibited without the prior written approval of GTM.
  - GTM reserves the right to make changes to its products without notice.
  - GTM semiconductor products are not warranted to be suitable for use in life-support Applications, or systems.
  - GTM assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.
- Head Office And Factory:**
- **Taiwan:** No. 17-1 Tatung Rd. Fu Kou Hsin-Chu Industrial Park, Hsin-Chu, Taiwan, R. O. C.  
TEL : 886-3-597-7061 FAX : 886-3-597-9220, 597-0785
  - **China:** (201203) No.255, Jiang-Jiang Tsai-Lueng RD. , Pu-Dung-Hsin District, Shang-Hai City, China  
TEL : 86-21-5895-7671 ~ 4 FAX : 86-21-38950165